Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Data and signal line chokes

Common-mode chokes, ring core, EIA 1812
0.011 … 0.47 mH, 200 … 300 mA, 60 °C

Series/Type: **B82799C0/S0**

Date: October 2008

EPCOS AG is a TDK Group Company.

Common-mode chokes, ring core, EIA 1812

SMD

Rated voltage 42 V AC/80 V DC
Rated inductance 0.011 mH to 0.47 mH
Rated current 200 mA to 300 mA

Construction

- Current-compensated ring core double choke
- Ferrite core
- LCP case (UL 94 V-0)
- Silicone potting
- Bifilar winding (B82799C0)
- Sector winding (B82799S0)

Features

- 150 °C version
- Qualified to AEC-Q200
- Suitable for reflow soldering
- Suitable for conductive adhesion due gold-plated terminals
- RoHS-compatible

Function

- B82799C0:
  Suppression of asymmetrical interference coupled in on lines, whereas data signals up to some MHz can pass unaffectedly.
- B82799S0:
  Suppression of asymmetrical and symmetrical interference (by L_{stray}) coupled in on lines. The high-frequency portions of the symmetrical data signal are decreased so far that EMC problems can be significantly reduced.

Applications

- Automotive applications, e.g. CAN bus

Terminals

- Base material CuSn6
- Layer composition Ni, Ag, Au
- Electro-plated

Marking

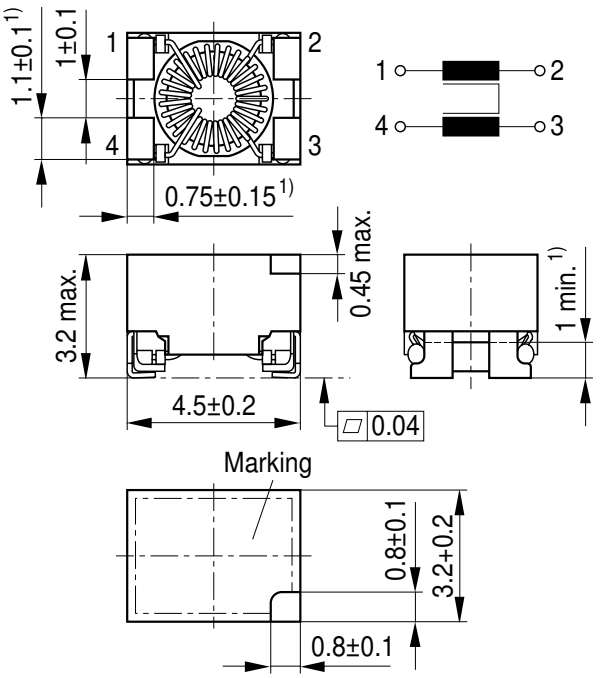
- Marking on component: Manufacturer, bifilar or sector winding (coded), L value (nH, coded), date of manufacture (YWWD)
- Minimum data on reel: Manufacturer, ordering code, L value and tolerance, quantity, date of packing

Delivery mode and packing unit

- 12-mm blister tape, wound on 330-mm ∅ reel
- Packing unit: 2500 pcs./reel

SMD

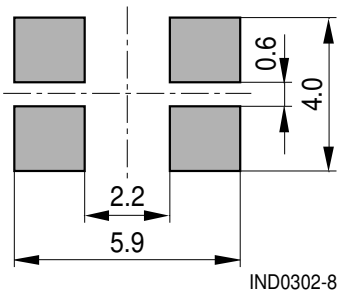
Dimensional drawing and pin configuration



1) Soldering area

IND0301-6-E

Layout recommendation

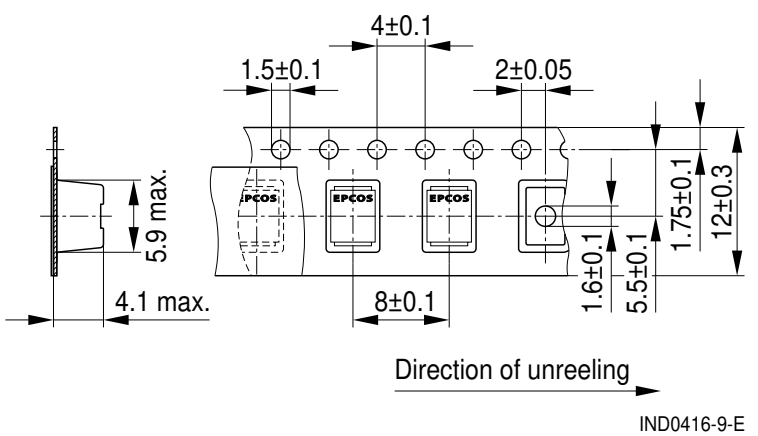


IND0302-8

Dimensions in mm

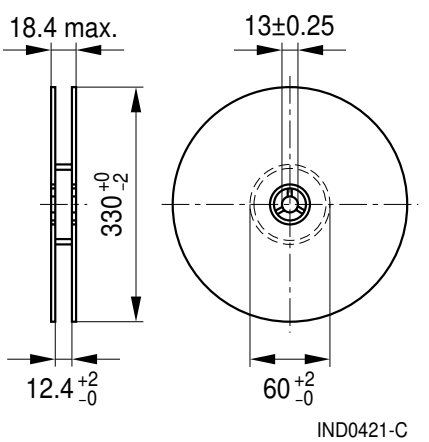
Taping and packing

Blister tape



IND0416-9-E

Reel



IND0421-C

Dimensions in mm

SMD

Technical data and measuring conditions

Rated voltage V_R	42 V AC (50/60 Hz) / 80 V DC
Rated temperature T_R	60 °C
Rated current I_R	Referred to 50 Hz and rated temperature
Applicable current I_R for high temperature applications	$0.5 \times I_R$, referred to 50 Hz and 150 °C ambient temperature
Rated inductance L_R	Measured with Agilent 4284A at 100 kHz, 0.1 mA, 20 °C Inductance is specified per winding.
Inductance tolerance	±30% at 20 °C
Inductance decrease ΔL/L	< 10% at DC magnetic bias with I_R, 20 °C
Stray inductance $L_{stray,typ}$	Measured with Agilent 4284A, 5 mA, 20 °C, typical values Measuring frequency: $L_R \leq 11$ µH = 1 MHz $L_R > 11$ µH = 100 kHz
DC resistance R_{typ}	Measured at 20 °C, typical values, specified per winding
Solderability	SnPb: (215 ±3) °C, (3 ±0.3) s Sn96.5Ag3.0Cu0.5: (245 ±5) °C, (3 ±0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-58)
Resistance to soldering heat	(260 ±5) °C, (10 ±1) s (to IEC 60068-2-58)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions (packaged)	–25 °C … +40 °C, ≤ 75% RH
Weight	Approx. 0.09 g

Characteristics and ordering codes

L_R mH	$L_{stray,typ}$ nH	I_R mA	R_{typ} mΩ	V_{test} V DC, 2 s	Ordering code
0.011	40	300	120	250	B82799C0113N001
0.022	60	250	170	250	B82799C0223N001
0.022	1200	250	170	250	B82799S0223N001
0.033	70	200	200	250	B82799C0333N001
0.033	1500	200	200	250	B82799S0333N001
0.051	90	200	250	250	B82799C0513N001
0.051	2300	200	250	250	B82799S0513N001
0.10	50	300	150	750	B82799C0104N001
0.22	60	200	200	750	B82799C0224N001
0.33	70	200	250	750	B82799C0334N001
0.47	100	200	320	750	B82799C0474N001

Sample kit available. Ordering code: B82799X001
For more information refer to chapter “Sample kits”.

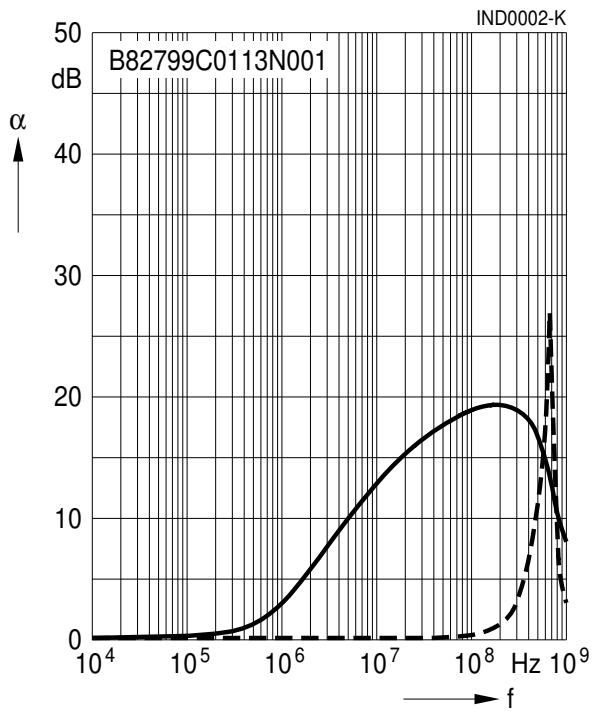
SMD

Insertion loss α (typical values at |Z| = 50 Ω, 20 °C)

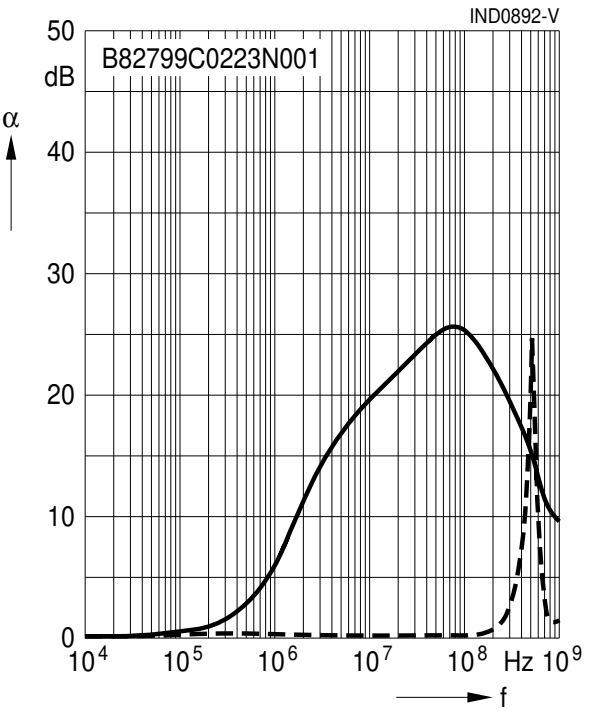
——— asymmetrical, all branches in parallel (common mode)

- - - - - - - symmetrical (differential mode)

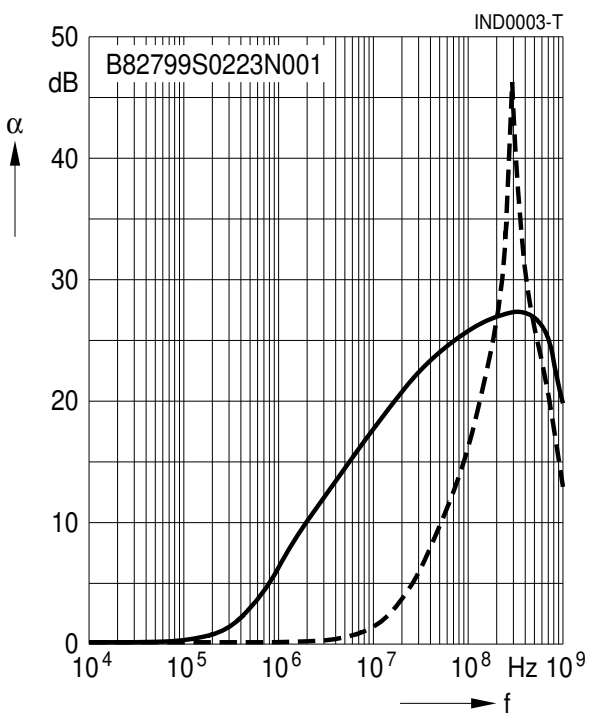
L_R = 0.011 mH



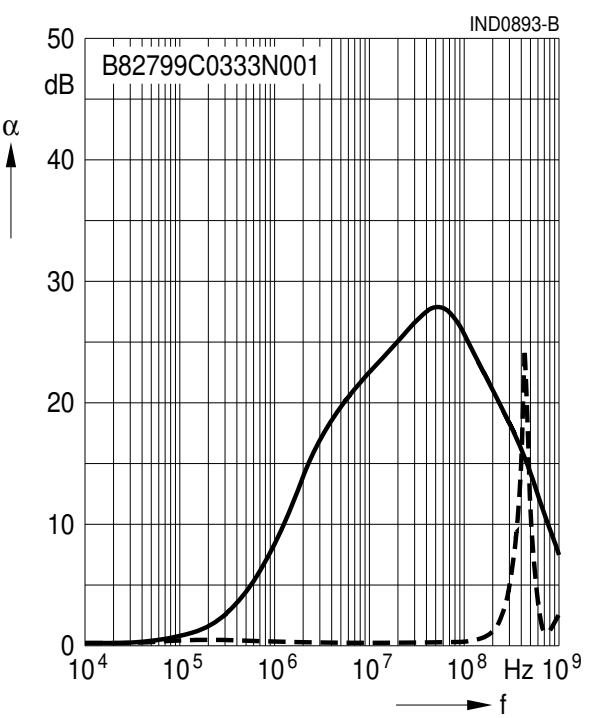
L_R = 0.022 mH (low L_{stray})



L_R = 0.022 mH (high L_{stray})



L_R = 0.033 mH (low L_{stray})



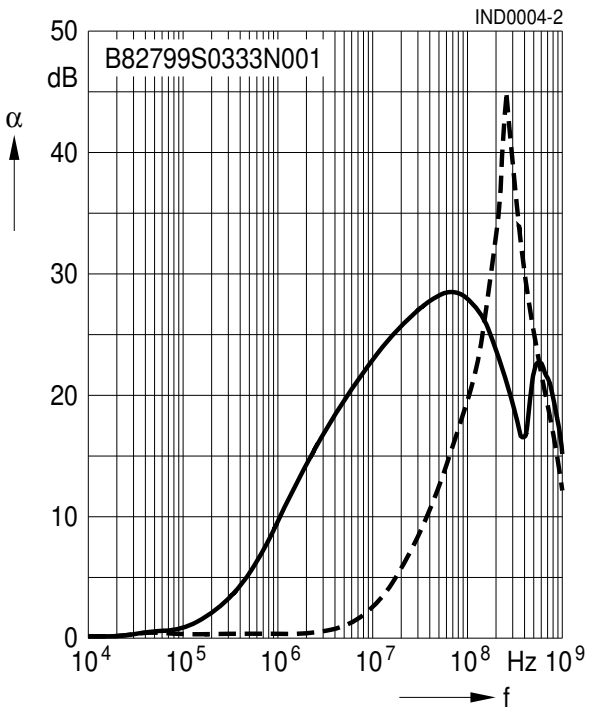
SMD

Insertion loss α (typical values at |Z| = 50 Ω, 20 °C)

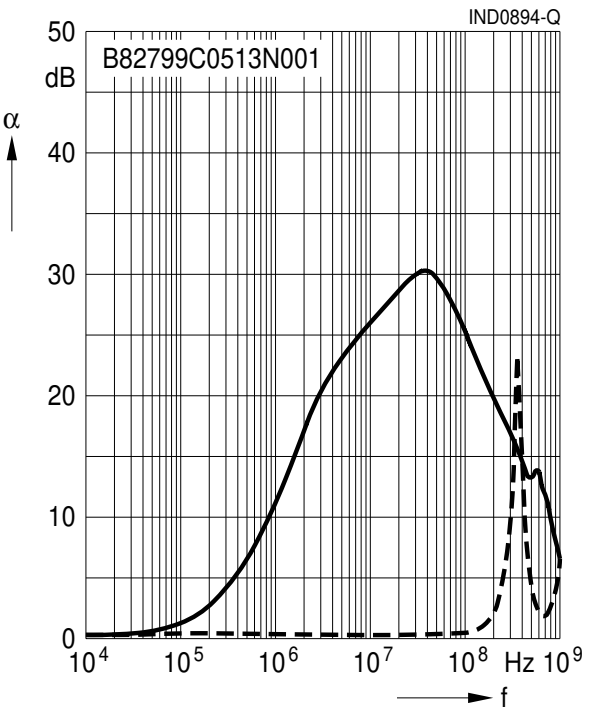
——— asymmetrical, all branches in parallel (common mode)

- - - - - - - symmetrical (differential mode)

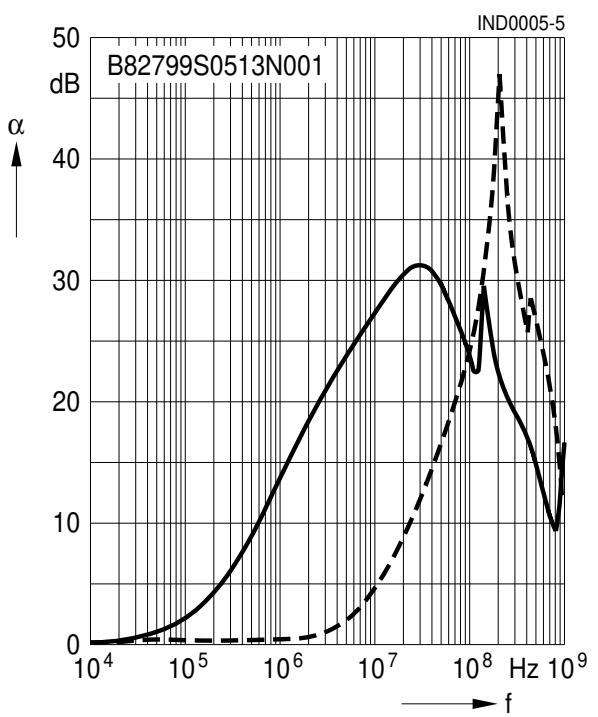
L_R = 0.033 mH (high L_{stray})



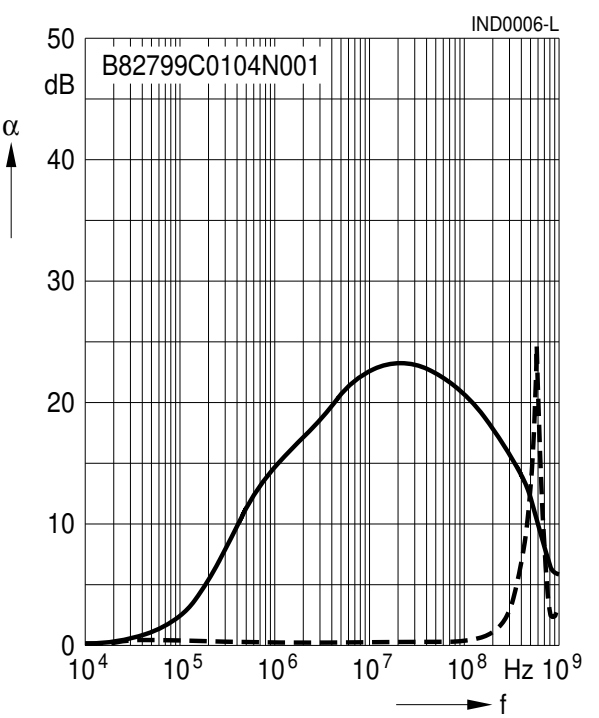
L_R = 0.051 mH (low L_{stray})



L_R = 0.051 mH (high L_{stray})



L_R = 0.10 mH



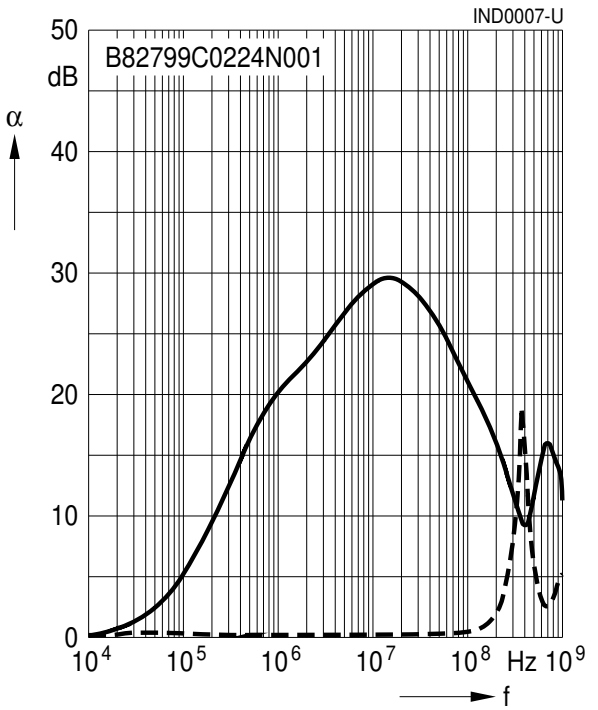
SMD

Insertion loss α (typical values at |Z| = 50 Ω, 20 °C)

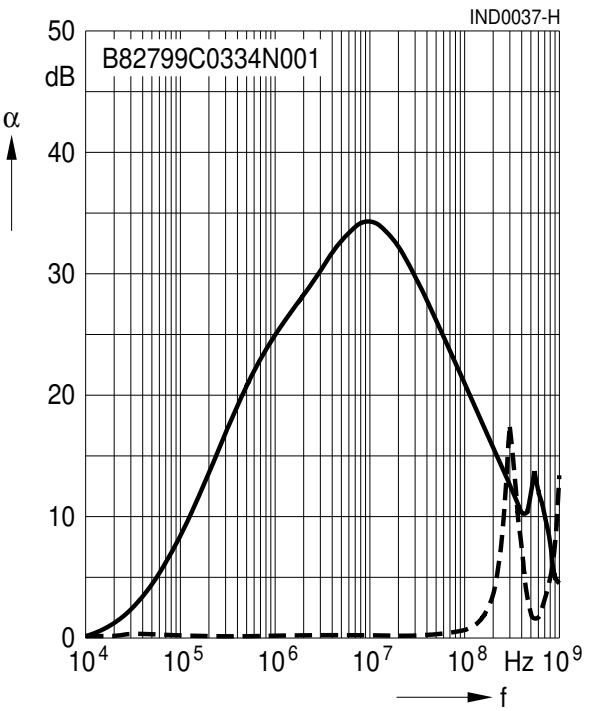
——— asymmetrical, all branches in parallel (common mode)

- - - - - - - symmetrical (differential mode)

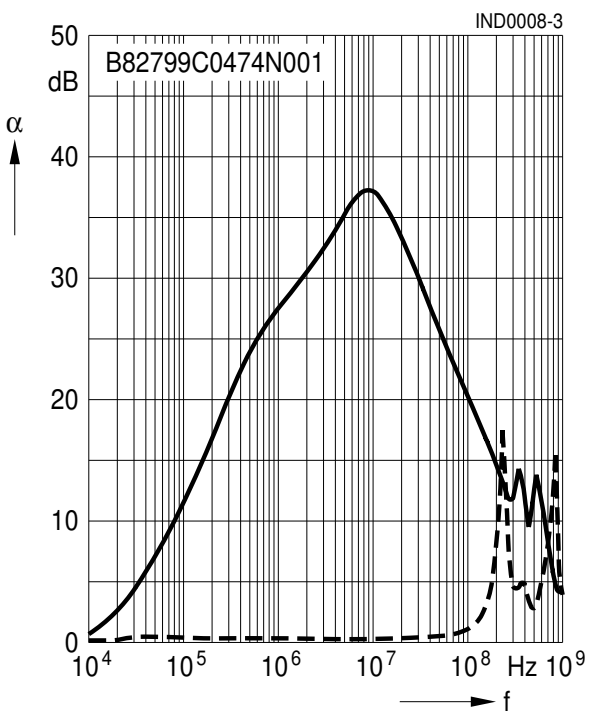
L_R = 0.22 mH



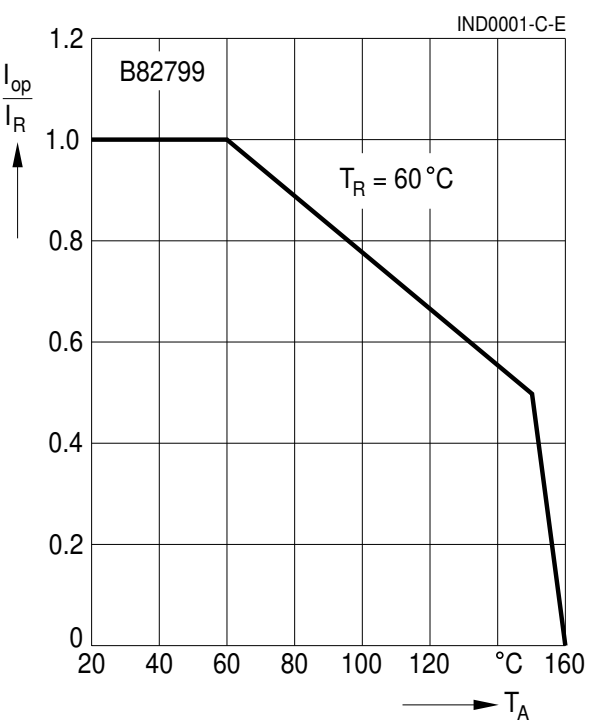
L_R = 0.33 mH



L_R = 0.47 mH



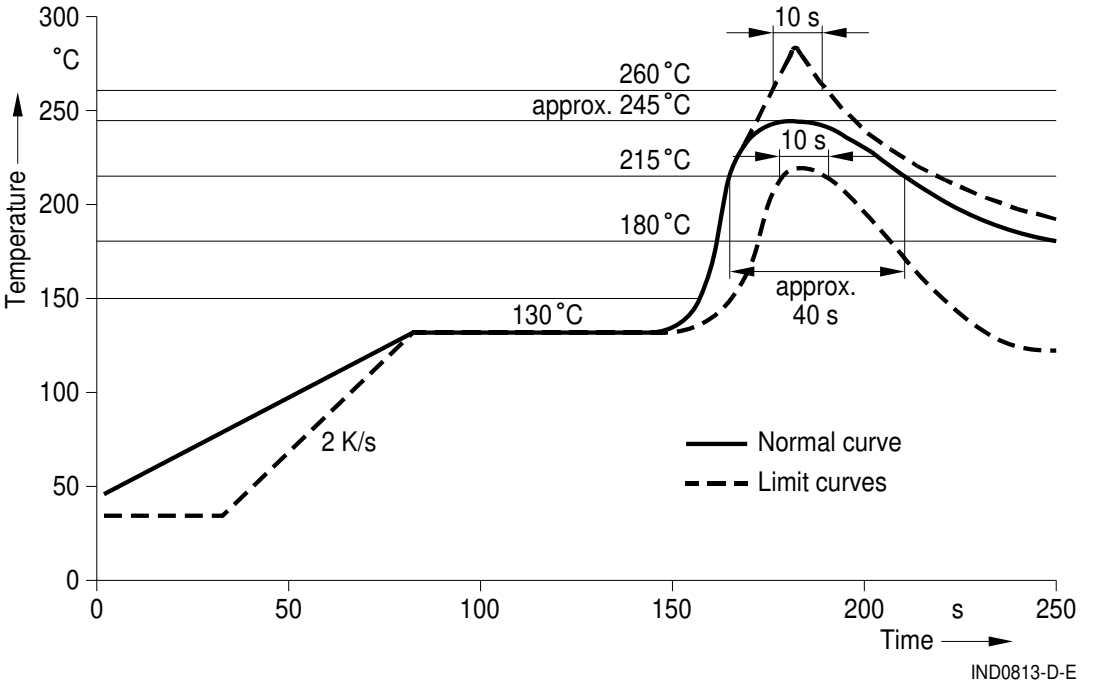
Current derating I_{op}/I_R versus ambient temperature



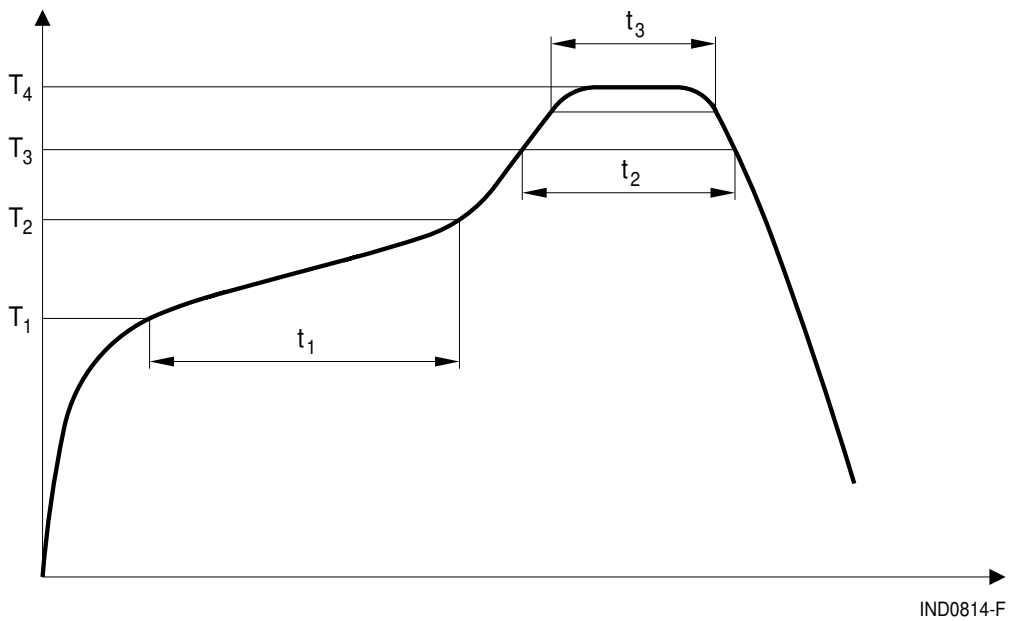
SMD

Recommended reflow soldering curve

Pb containing solder material (based on CECC 00802 edition 2)



Pb-free solder material (based on JEDEC J-STD 020C)



T_1 °C	T_2 °C	T_3 °C	T_4 °C	t_1 s	t_2 s	t_3 s
150	200	217	250	< 110	< 90	< 40 @ T_4 –5 °C

Time from 25 °C to T_4: max 300 s
Maximal numbers of reflow cycles: 3

Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  - Particular attention should be paid to the derating curves given there.
  - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application.**

   As a rule, EPCOS is either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether an EPCOS product with the properties described in the product specification is suitable for use in a particular customer application.

2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified.** In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.

3. **The warnings, cautions and product-specific notes must be observed**.

4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. because they are classed as hazardous)**. Useful information on this will be found in our Material Data Sheets on the Internet (www.epcos.com/material). Should you have any more detailed questions, please contact our sales offices.

5. We constantly strive to improve our products. Consequently, **the products described in this publication may change from time to time**. The same is true of the corresponding product specifications. Please check therefore to what extent product descriptions and specifications contained in this publication are still applicable before or when you place an order.

   We also **reserve the right to discontinue production and delivery of products**. Consequently, we cannot guarantee that all products named in this publication will always be available.

   The aforementioned does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

6. Unless otherwise agreed in individual contracts, **all orders are subject to the current version of the "General Terms of Delivery for Products and Services in the Electrical Industry" published by the German Electrical and Electronics Industry Association (ZVEI)**.

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